

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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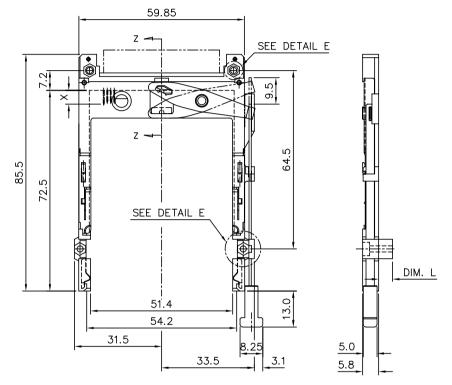
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



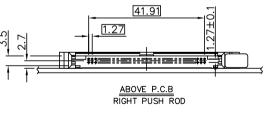




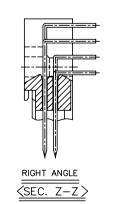
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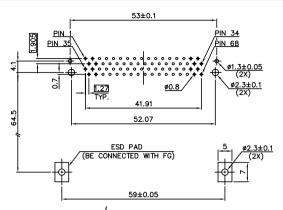


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NOTES:

4 CARD INSERTION DIRECTION RECOMMENDED FOOT PRINT(MOUNTED SIDE)

- (1) PUSH ROD LOCATION AND PCB SIDE ARE AS APPEARS INSTALLED.
- 2. MATERIAL
 - 2.1 HEADER ASS'Y:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-O BLACK PIN : COPPER ALLOY

2.2 EJECT MECHANISM ASS'Y:

PLASTIC: HIGH TEMPERATURE THERMOPLASTICUL94V-O BLACK PLATE AND PUSH ROD : STAINLESS

EMI CONTACT: COPPER ALLOY

3. FINISH (PIN)

UNDER PLATING : 0.5 µm MIN. Ni

CONTACT AREA: 0.1 µm MIN. GOLD OVER 0.5 µm MIN. Pd-Ni

SOLDER TAIL : 2.5 µm MIN. PURE TIN

4. DIM "X"

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NO.	OTHERS	36,67	1,17,34,35,51,68

- 5. PRODUCT SPEC: 110-263
- 6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- 8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

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PDS: Rev :A3

В

form: A4mmXLc

STATUS:Released

Printed: Apr 26,42012

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